EVVOSEMI®
THINK CHANGE DO

ESD TVS MOS LDO Diode Sensor DC-DC

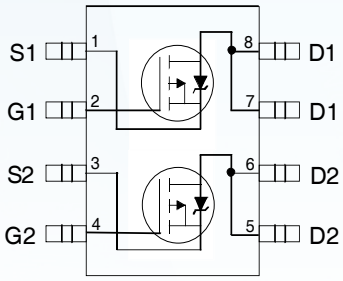
Product Specification

Domestic Part Number	IRF7328
Overseas Part Number	IRF7328
Equivalent Part Number	IRF7328

Dual P-Channel 30 V (D-S) MOSFET

Features

- Trench Technology
- Ultra Low On-Resistance
- Dual P-Channel MOSFET
- Available in Tape & Reel
- Lead-Free



Top View

V_{DSS}	$R_{DS(on)}$ max	I_D
-30V	21mΩ@V_{GS} = -10V	-8.0A
	32mΩ@V_{GS} = -4.5V	-6.8A

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{DS}	Drain-Source Voltage	-30	V
I_D @ T_A = 25°C	Continuous Drain Current, V_{GS} @ -10V	-8.0	A
I_D @ T_A = 70°C	Continuous Drain Current, V_{GS} @ -10V	-6.4	
I_{DM}	Pulsed Drain Current①	-32	
P_D @T_A = 25°C	Maximum Power Dissipation③	2.0	W
P_D @T_A = 70°C	Maximum Power Dissipation③	1.3	W
	Linear Derating Factor	16	mW/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
T_J , T_{STG}	Junction and Storage Temperature Range	-55 to + 150	°C

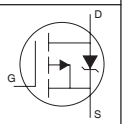
Thermal Resistance

	Parameter	Max.	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient ③	62.5	°C/W

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-30	——	——	V	V_{GS} = 0V, I_D = -250μA
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	——	-0.018	——	V/°C	Reference to 25°C, I_D = -1mA
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	——	17	21	mΩ	V_{GS} = -10V, I_D = -8.0A ②
		——	26.8	32		V_{GS} = -4.5V, I_D = -6.8A ②
$V_{GS(th)}$	Gate Threshold Voltage	-1.0	——	-2.5	V	V_{DS} = V_{GS}, I_D = -250μA
g_{fs}	Forward Transconductance	12	——	——	S	V_{DS} = -10V, I_D = -8.0A
I_{DSS}	Drain-to-Source Leakage Current	——	——	-15	μA	V_{DS} = -24V, V_{GS} = 0V
		——	——	-25		V_{DS} = -24V, V_{GS} = 0V, T_J = 70°C
I_{GSS}	Gate-to-Source Forward Leakage	——	——	-100	nA	V_{GS} = -20V
	Gate-to-Source Reverse Leakage	——	——	100		V_{GS} = 20V
Q_g	Total Gate Charge	——	52	78	nC	I_D = -8.0A
Q_{gs}	Gate-to-Source Charge	——	9.8	——		V_{DS} = -15V
Q_{gd}	Gate-to-Drain ("Miller") Charge	——	8.3	——		V_{GS} = -10V
$t_{d(on)}$	Turn-On Delay Time	——	13	20	ns	V_{DD} = -15V, V_{GS} = -10.0V
t_r	Rise Time	——	15	23		I_D = -1.0A
$t_{d(off)}$	Turn-Off Delay Time	——	198	297		R_G = 6.0Ω
t_f	Fall Time	——	98	147		R_D = 15Ω ②
C_{iss}	Input Capacitance	——	2675	——	pF	V_{GS} = 0V
C_{oss}	Output Capacitance	——	409	——		V_{DS} = -25V
C_{rss}	Reverse Transfer Capacitance	——	262	——		f = 1.0MHz

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	——	——	-2.0	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	——	——	-32		
V_{SD}	Diode Forward Voltage	——	——	-1.2	V	T_J = 25°C, I_S = -2.0A, V_{GS} = 0V ②
t_{rr}	Reverse Recovery Time	——	37	56	ns	T_J = 25°C, I_F = -2.0A
Q_{rr}	Reverse Recovery Charge	——	36	54	nC	di/dt = -100A/μs ②

Notes:

① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width ≤ 400μs; duty cycle ≤ 2%.

③ Surface mounted on FR-4 board, t ≤ 10sec.

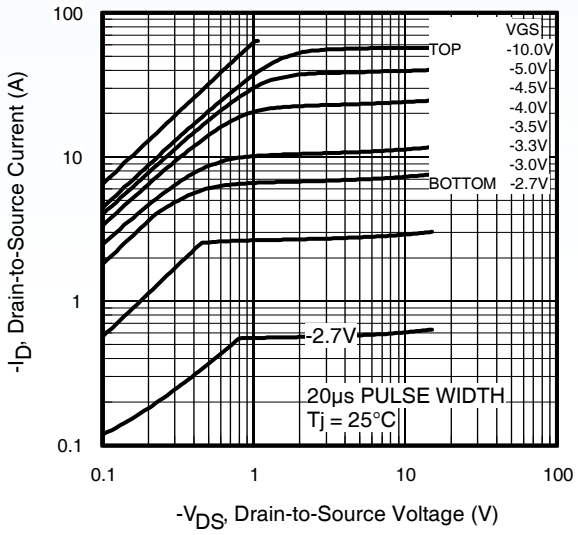


Fig 1. Typical Output Characteristics

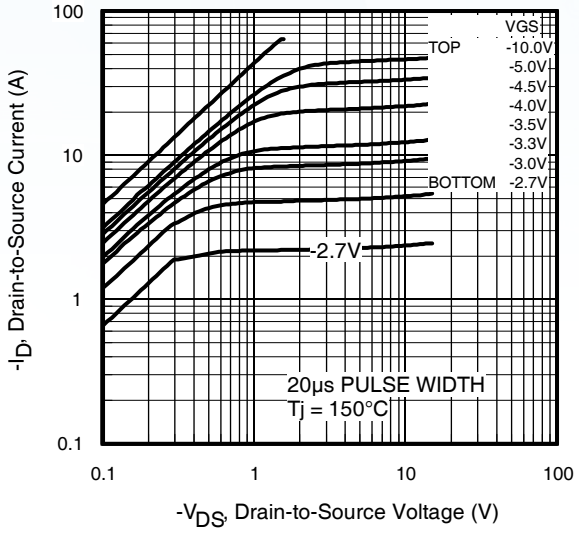


Fig 2. Typical Output Characteristics

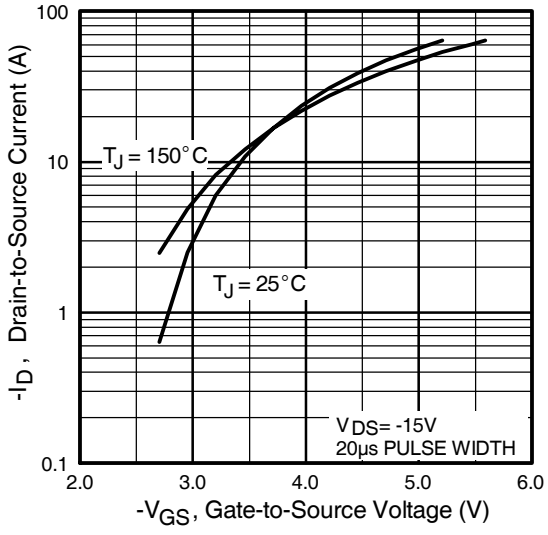


Fig 3. Typical Transfer Characteristics

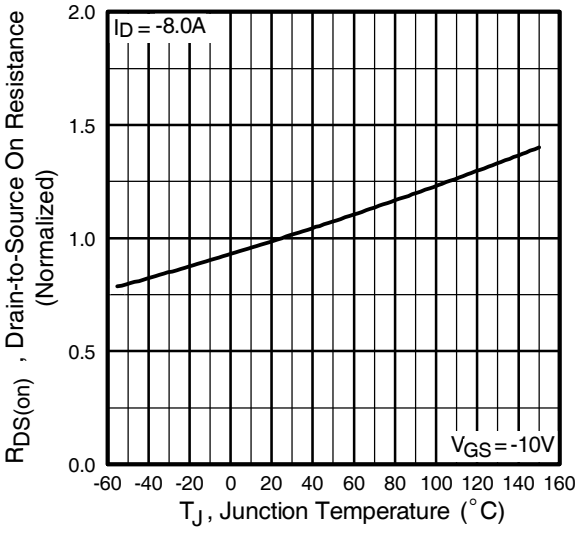


Fig 4. Normalized On-Resistance Vs. Temperature

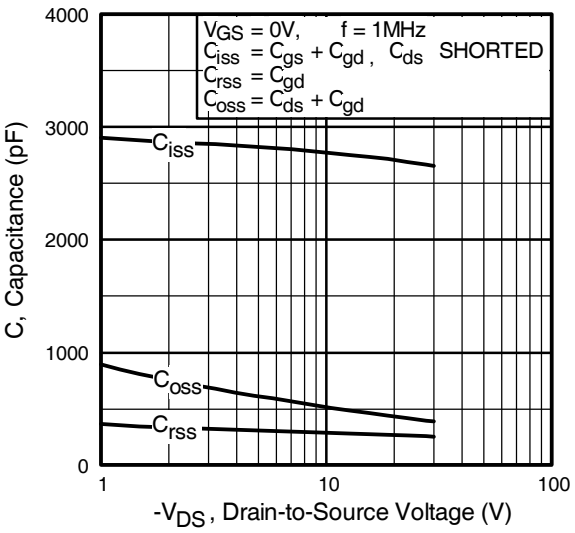


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

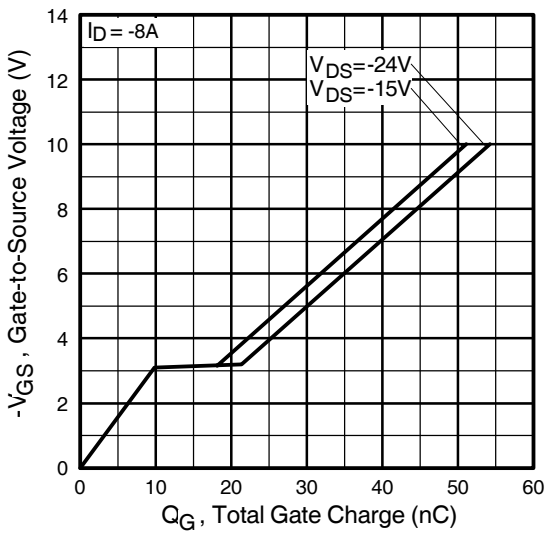


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

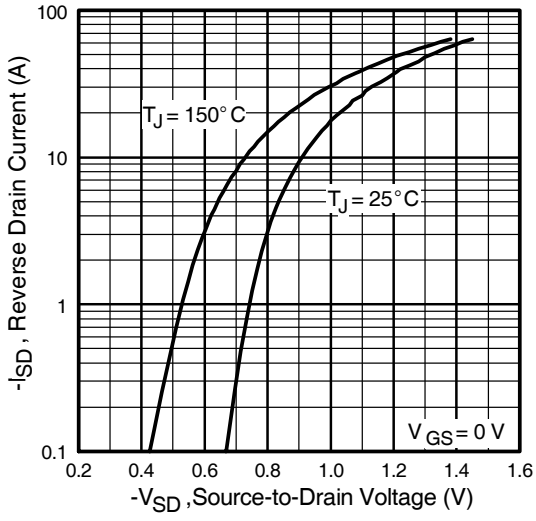


Fig 7. Typical Source-Drain Diode Forward Voltage

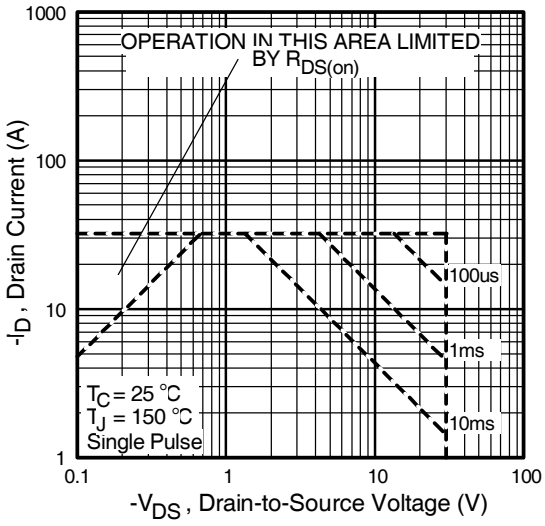


Fig 8. Maximum Safe Operating Area

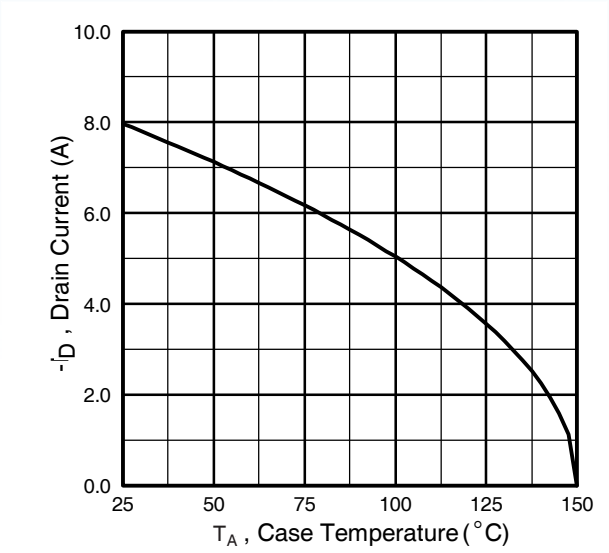


Fig 9. Maximum Drain Current Vs. Case Temperature

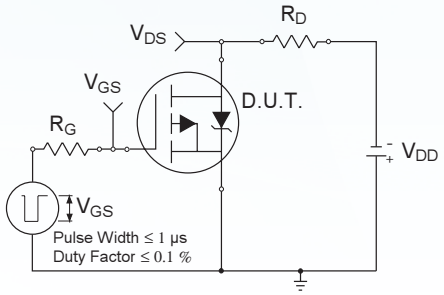


Fig 10a. Switching Time Test Circuit

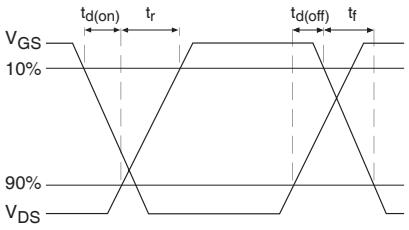


Fig 10b. Switching Time Waveforms

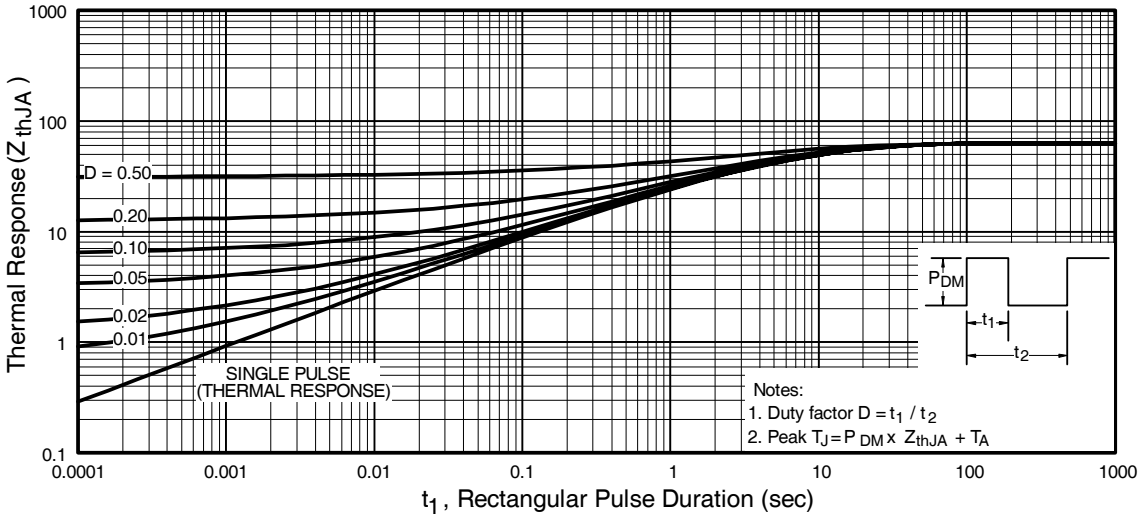


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

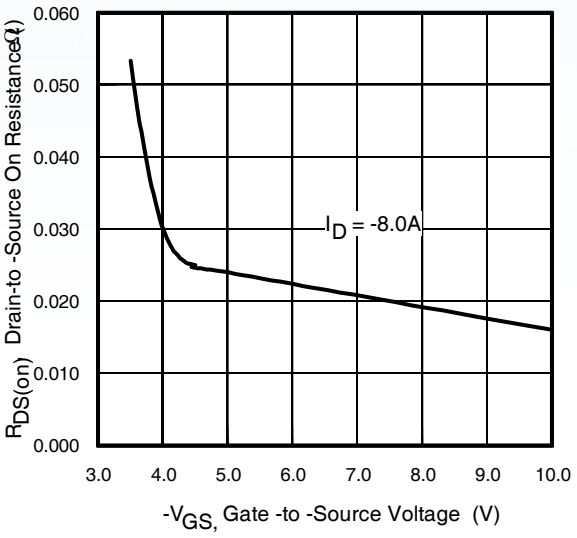


Fig 12. Typical On-Resistance Vs. Gate Voltage

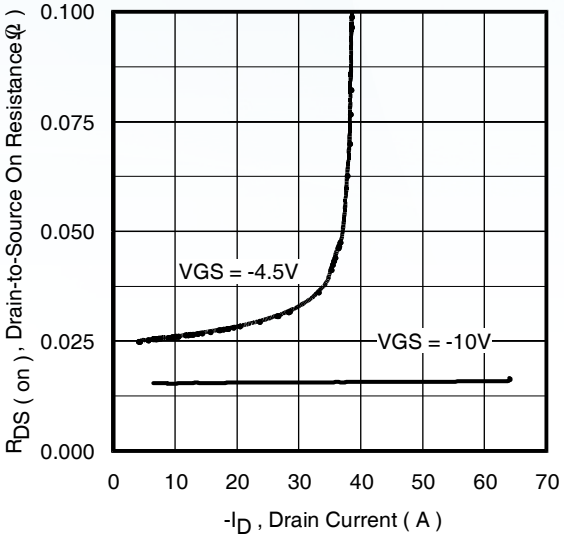


Fig 13. Typical On-Resistance Vs. Drain Current

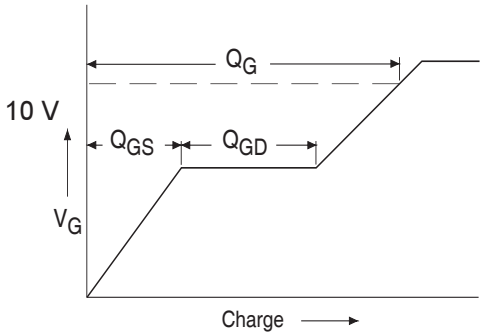


Fig 14a. Basic Gate Charge Waveform

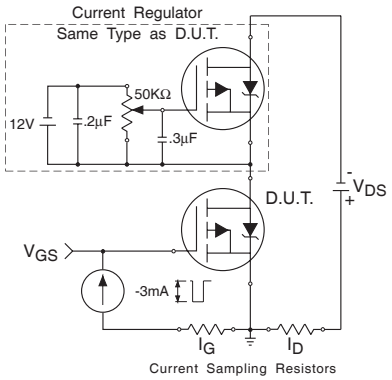
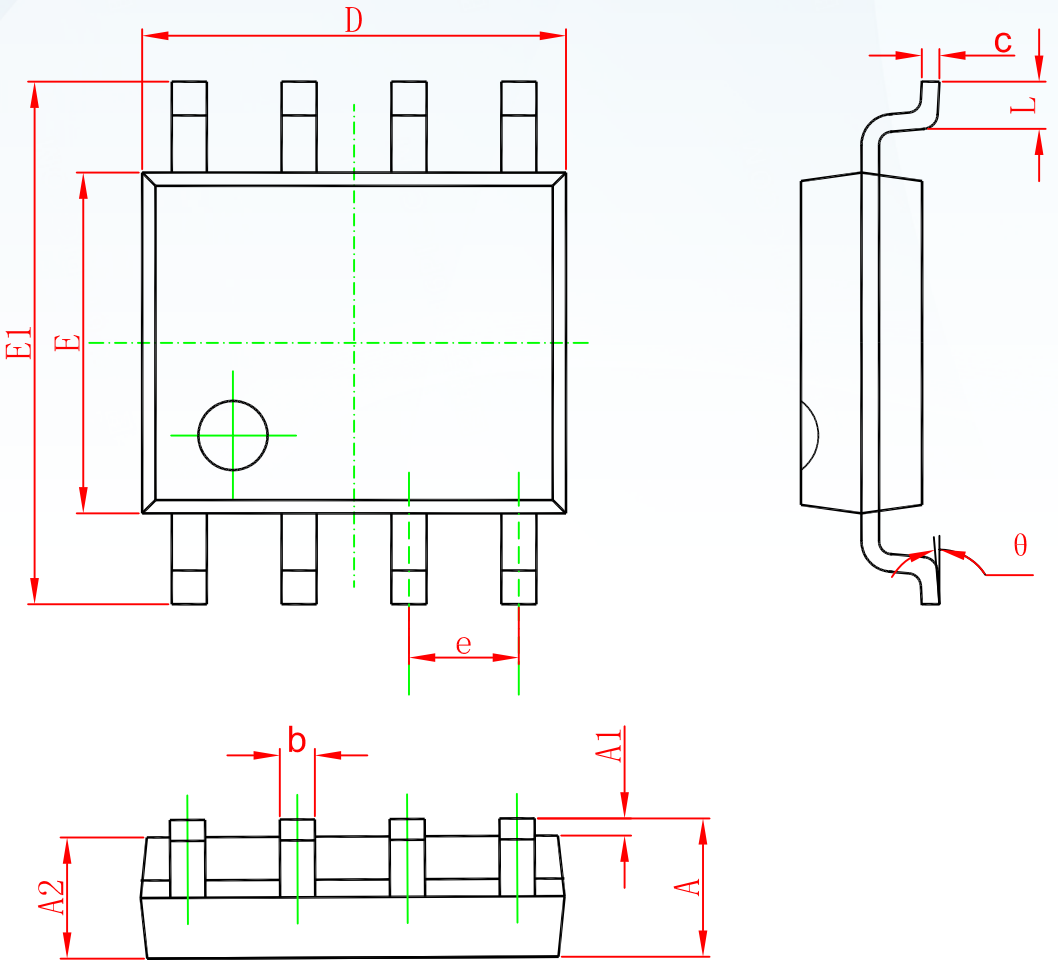


Fig 14b. Gate Charge Test Circuit

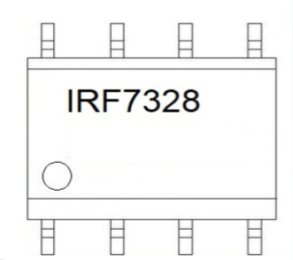
Dual P-Channel 30 V (D-S) MOSFET

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
IRF7328	SOP-8	3000	Tape and reel

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